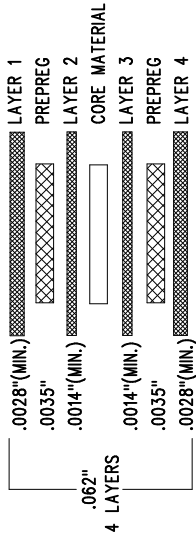


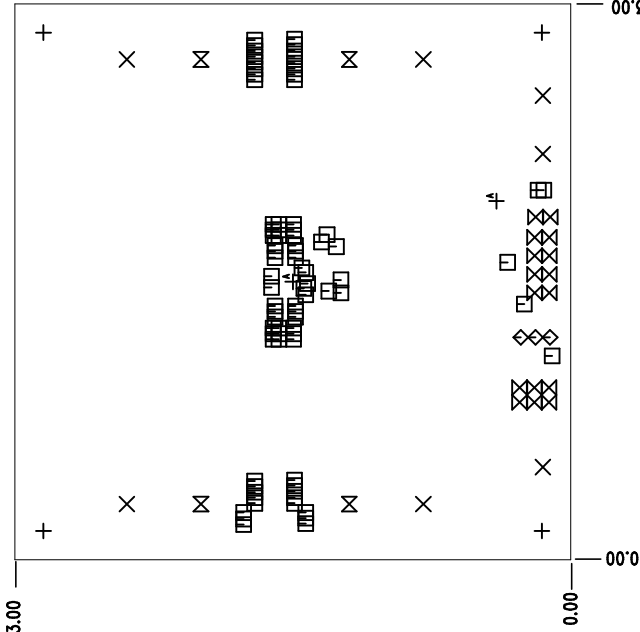
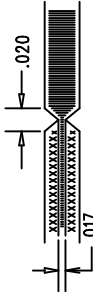
REVISION HISTORY			
ECO	REV	DESCRIPTION	APP. ENG.
-	1	PROTOTYPE	Ling J.
			8-15-19

LAYER STRUCTURE



NOTES: UNLESS OTHERWISE SPECIFIED

1. FAB PER IPC-A-600.
2. MATERIAL: -LEAD FREE ASSEMBLY COMPLIANT, ISOLA FR-370HR OR EQUIVALENT.
 - FINISHED THICKNESS TO BE 0.062 +/- .005
 - TOTAL OF 4 LAYERS WITH 2 OZ. CU ON THE OUTER LAYERS AND 1 OZ. CU ON THE INNER LAYERS.
 - FLAMMABILITY RATING: 94 V-0 MINIMUM.
3. SIZE: CUT TO DIMENSIONS AND TOLERANCES SHOWN.
 - 0.00 ARE PRIMARY DATUMS.
4. DRILLING: -DRILL HOLES PER SCHEDULE. PLATE THROUGH HOLES WITH COPPER, 0.001" THICK MIN.
 - ALL HOLE SIZES ARE SPECIFIED AFTER PLATING.
 - HOLE LOCATION TOLERANCES ARE +/-0.003" IN RELATION TO CENTER
5. FINISH: -SMOBC USING LPI BOTH SIDES, COLOR GREEN.
 - GOLD IMMERSION BOTH SIDES.
 - FOR SILKSCREENS: USE WHITE NON-CONDUCTIVE INK.
 - DO NOT ALTER ARTWORK e.g. TO ADD LOGO OR DATE CODE.
7. PCBs ARE TO BE RoHS COMPLIANT.
8. DESIGN HAS SOLDER MASK DEFINED PADS ON U1.
 - U1 SOLDER MASK SIZE IS 0.0177 (0.35mm) AND PAD SIZE IS 0.0236(0.45mm)
 - DON'T CHANGE PAD SIZE OR SOLDER MASK SIZE.
9. PLUG ALL VIAS WITH EPOXY.
10. SCORING FOR PANELIZED PCB (PRODUCTION FAB ONLY):
 - AND PLATE OVER, PLANARIZE FINAL SURFACE.



SIZE	QTY	SYM	PLATED	TOL
0.187	4	+	YES	+/-0.003
0.09528	7	X	YES	+/-0.003
0.012	80	□	YES	+/-0.003
0.03543	3	◇	YES	+/-0.003
0.035	16	⊗	YES	+/-0.003
0.205	4	⊗	YES	+/-0.003
0.004	2	⊕	YES	+/-0.003

UNLESS OTHERWISE SPECIFIED

DIMENSIONS ARE IN INCHES

TOLERANCES:

0.XX = ± 0.01

0.XXX = ± 0.005

INTERPRET DIM AND TOL

PER ASME Y14.5M-1994

THIRD ANGLE PROJECTION

APPROVALS

PCB DES.	Hz
APP ENG.	Ling J.

POWER BY LINEAR
1630 MCCARTHY BLVD
MILPITAS, CA 95035
PH: (408)432-1900
WWW.ANALOG.COM
FOR AD CUSTOMER USE ONLY

TITLE: FABRICATION DRAWING

1A BUCK-BOOST POWER MODULE REGULATOR

SIZE	IC NO.	REV
N/A	LTM4693EV	2
DEMO CIRCUIT 3016A		

SCALE = NONE

FILENAME: DC3016A2.PCB

SHT 1 OF 1